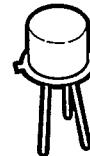


LT1839

High Frequency, High Voltage Transistor

Ideal for CRT Driver Applications

- High Voltage
- High Frequency
- Low Capacitance
- Rugged
- All Gold Metallization



TO-39 Package

These rugged NPN silicon transistors are specifically designed for CRT driver applications requiring high frequency and high voltage, such as high resolution color graphics video monitors.

A new process in wafer fabrication enables high breakdown voltage without sacrificing high frequency capability. Utilizing ion implantation techniques coupled with microwave processing,

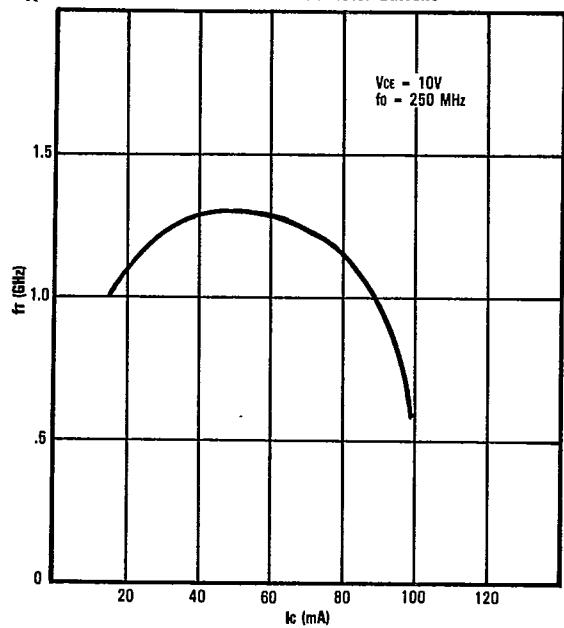
the LT1839 sets new standards for bipolar transistors in these applications. Gold metallization insures high reliability for these rugged devices.

Electrical Characteristics (25°C Unless otherwise noted)

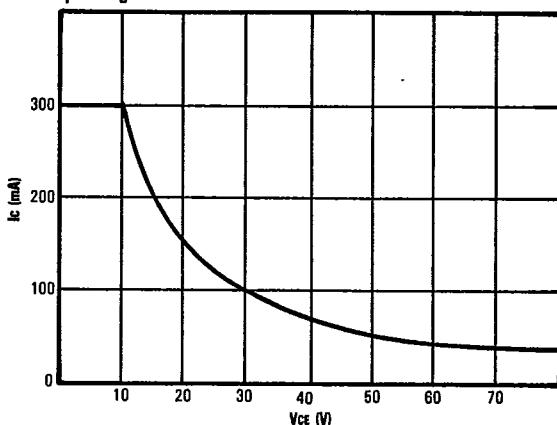
Symbol	Description	Conditions	Min.	Max.	Units
BV _{EBO}	Emitter-Base Breakdown-Voltage	I _E = .1mA	3.0		V
BV _{CBO}	Collector-Base Breakdown-Voltage	I _C = .1mA	120		V
BV _{CEO}	Collector-Emitter Breakdown-Voltage	I _C = 1mA	70		V
I _{CES}	Collector-Emitter Leakage	V _{CE} = 80V		100	µA
I _{CBO}	Collector-Base Leakage	V _{CB} = 80V		20	µA
H _{FE}	DC Current Gain	V _{CE} = 5V I _C = 50mA	15	45	
C _{CB}	Collector-Base Capacitance	V _{CB} = 10V		2.0	pF
V _{CE} (SAT)	Collector-Emitter Saturation Voltage	I _C = 50mA I _B = 5mA		800	mV
F _T	Gain Bandwidth Product	V _{CE} = 15V I _C = 50mA f _o = 200MHz	1.0		GHz
S ₂₁	Common Emitter Insertion Gain	V _{CE} = 15V I _C = 50mA f = 200MHz	13		dB

Collector Current (I _C)	Collector Base Voltage (V _{CBO})	Junction Temperature (T _J)	Storage Temperature (T _{STG})
300mA	120V	+200°C	-65°C to +200°C

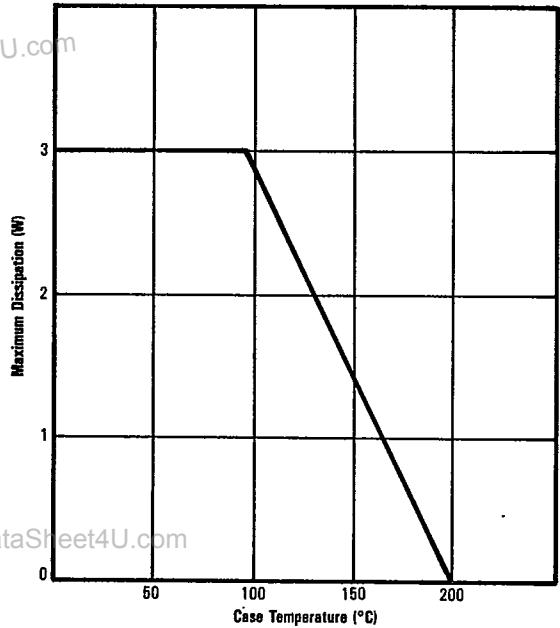
Typical Gain Bandwidth Product vs. Collector Current



Safe Operating Area



Dissipation vs. Temperature



Typical Junction Capacitance vs. Voltage

